

(52) **U.S. Cl.**
CPC **H01L27/124** (2013.01); **H01L 27/1248**
(2013.01); **H01L 21/76877** (2013.01); **H01L**
27/1244 (2013.01)

JP	2006215226	8/2006
TW	200632560 A	9/2006
TW	200841104 A	10/2008
TW	200910021 A	3/2009

(56) **References Cited**

U.S. PATENT DOCUMENTS

2004/0150809	A1	8/2004	Chang et al.
2004/0183084	A1	9/2004	Wachi
2005/0117094	A1	6/2005	Kim et al.
2008/0068540	A1	3/2008	Kang et al.
2008/0251790	A1	10/2008	Cheng
2009/0263921	A1	10/2009	Lee et al.
2009/0302406	A1	12/2009	Gambino et al.
2009/0309102	A1	12/2009	Kim et al.

FOREIGN PATENT DOCUMENTS

CN	101047194	A	10/2007
JP	2005014043	A	1/2005

OTHER PUBLICATIONS

English language translation of abstract and pertinent parts of TW 200910021 A (published Mar. 1, 2009).

English language translation of abstract and pertinent parts of TW 200632560 A (published Sep. 16, 2009).

English language translation of abstract of CN 101034222A (published Sep. 12, 2007).

English language translation of abstract of CN 101047194A (published Oct. 3, 2007).

English language translation of abstract of CN 1624552A (published Jun. 8, 2005).

English language translation of abstract of JP 2005014043A (published Jan. 20, 2005).

English language translation of abstract of JP 2006215226 (published Aug. 17, 2006).

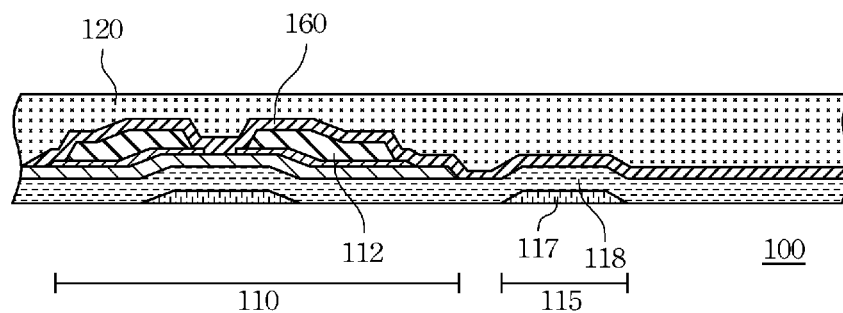


FIG. 1

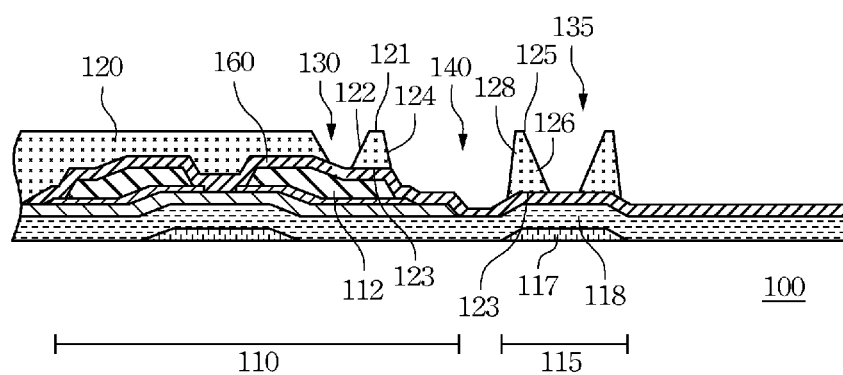


FIG. 2

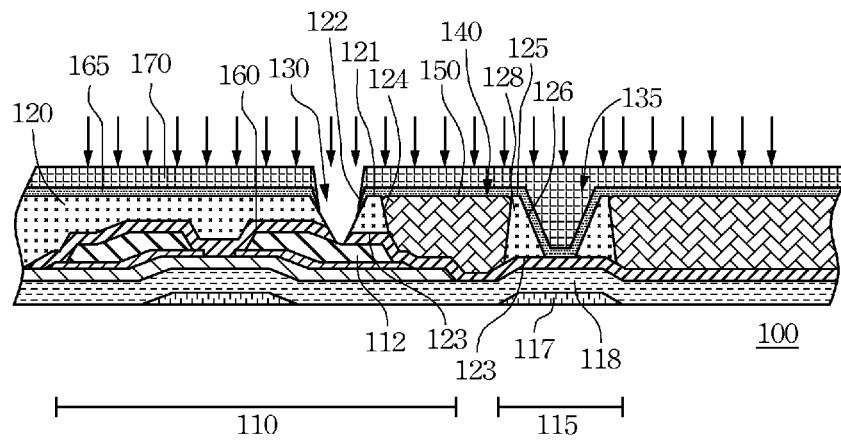


FIG. 5

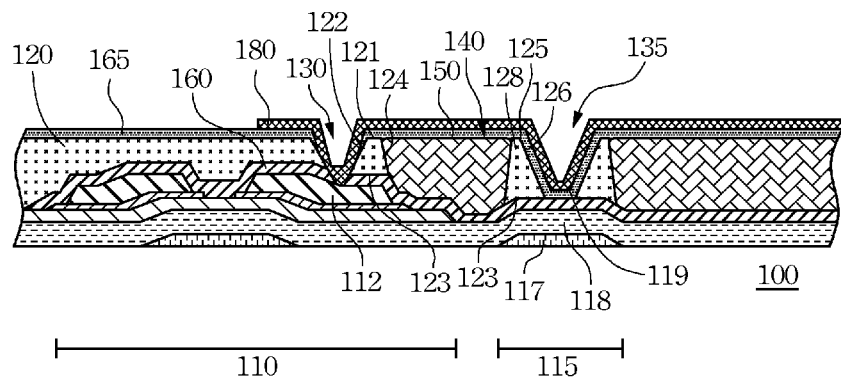


FIG. 6

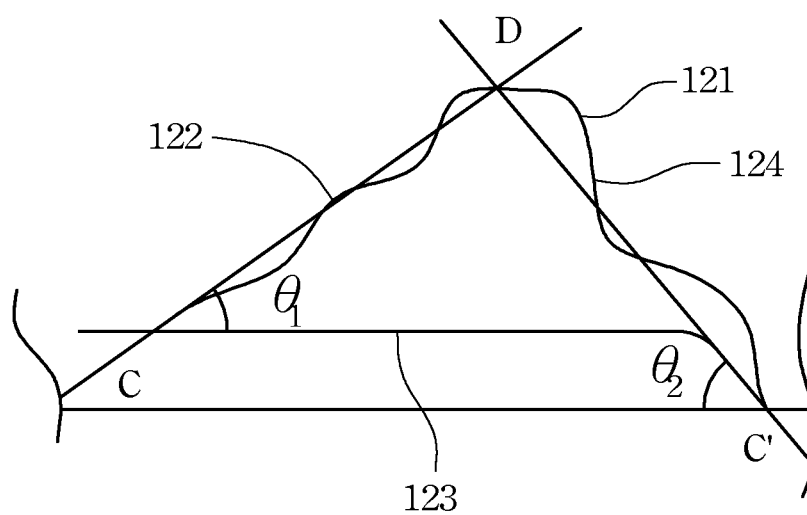
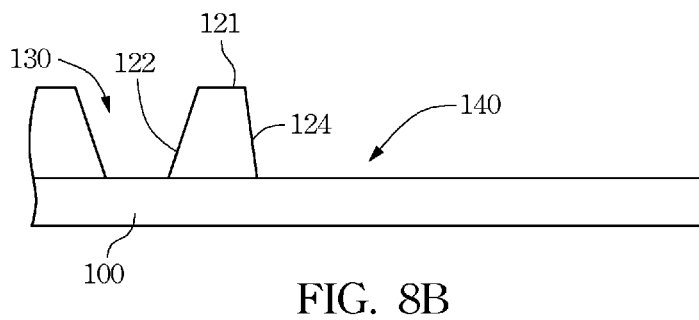
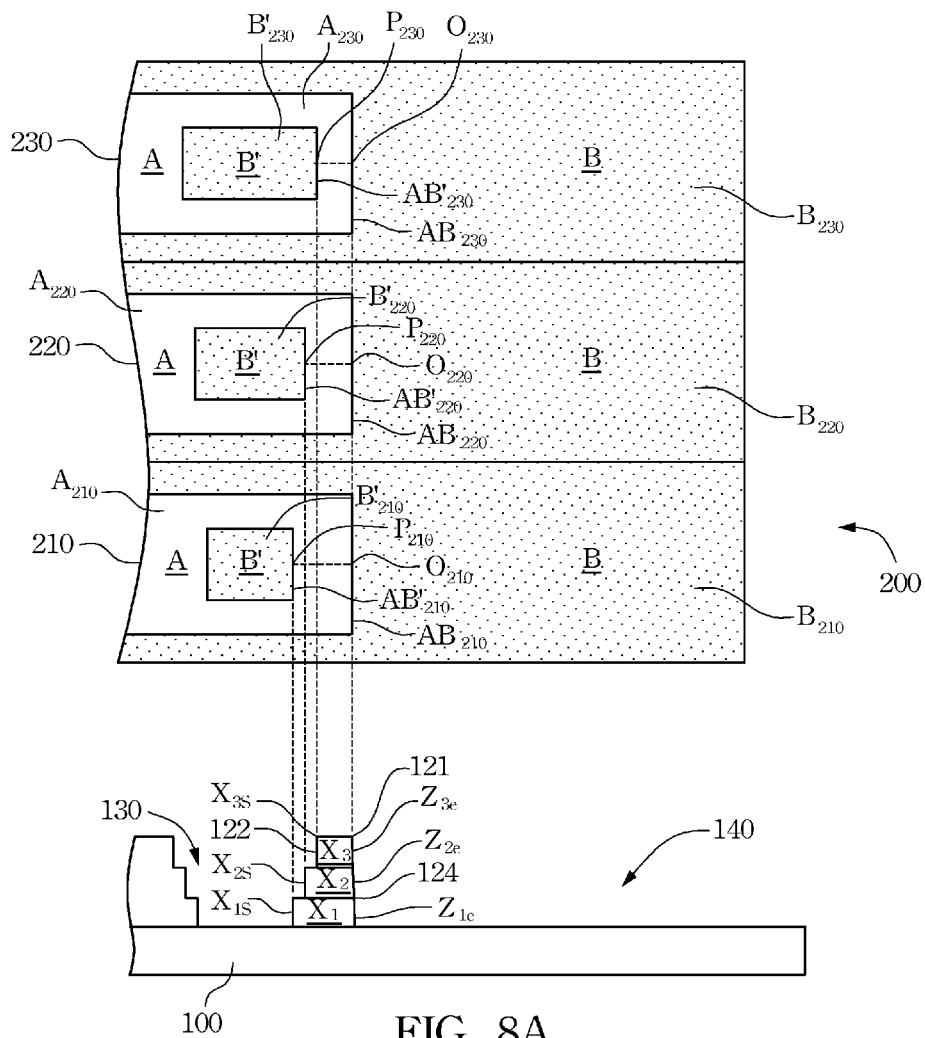


FIG. 7



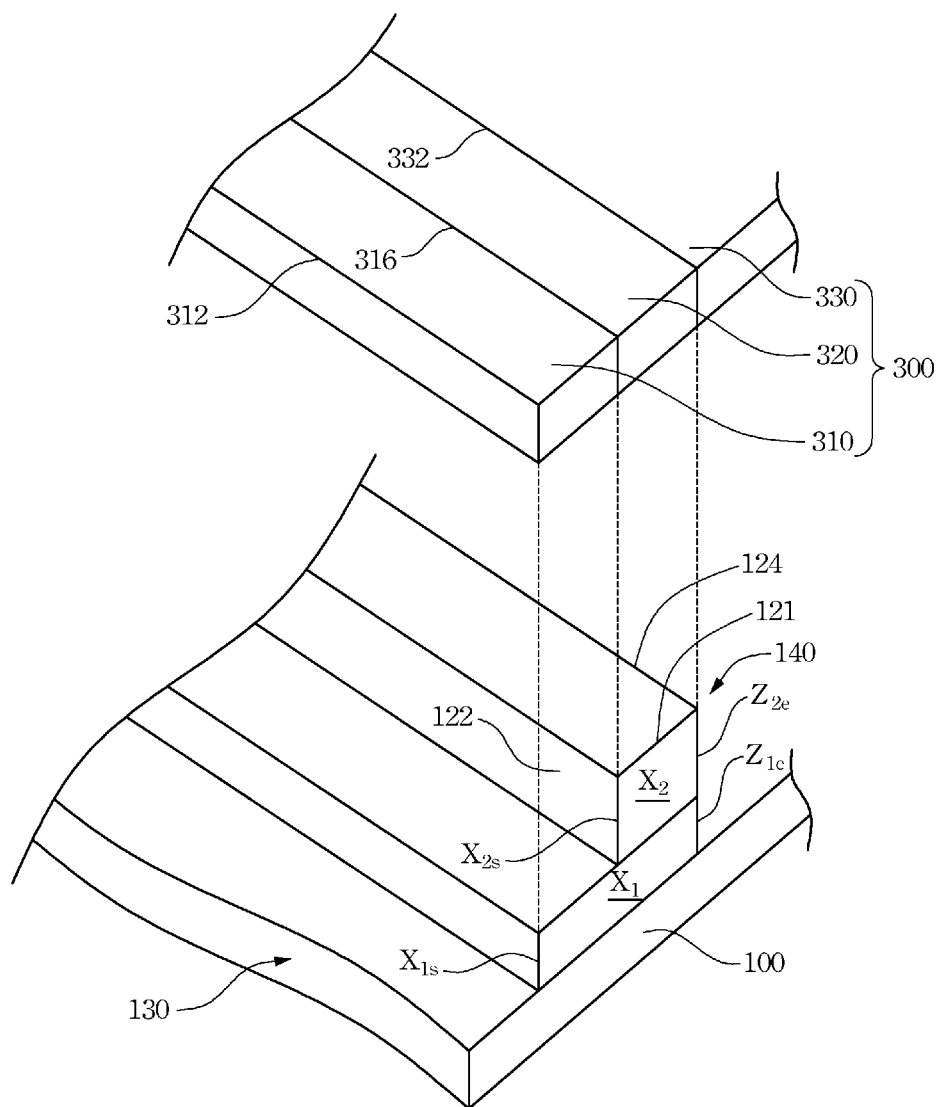


FIG. 9A

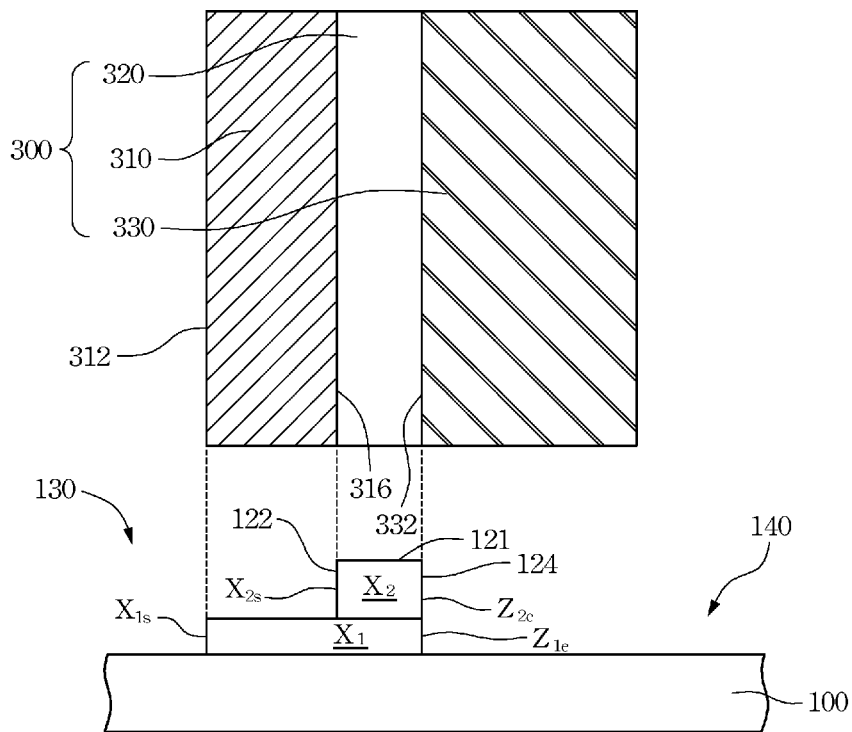


FIG. 9B

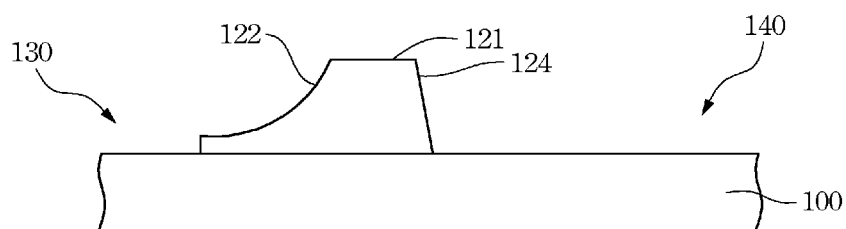


FIG. 9C

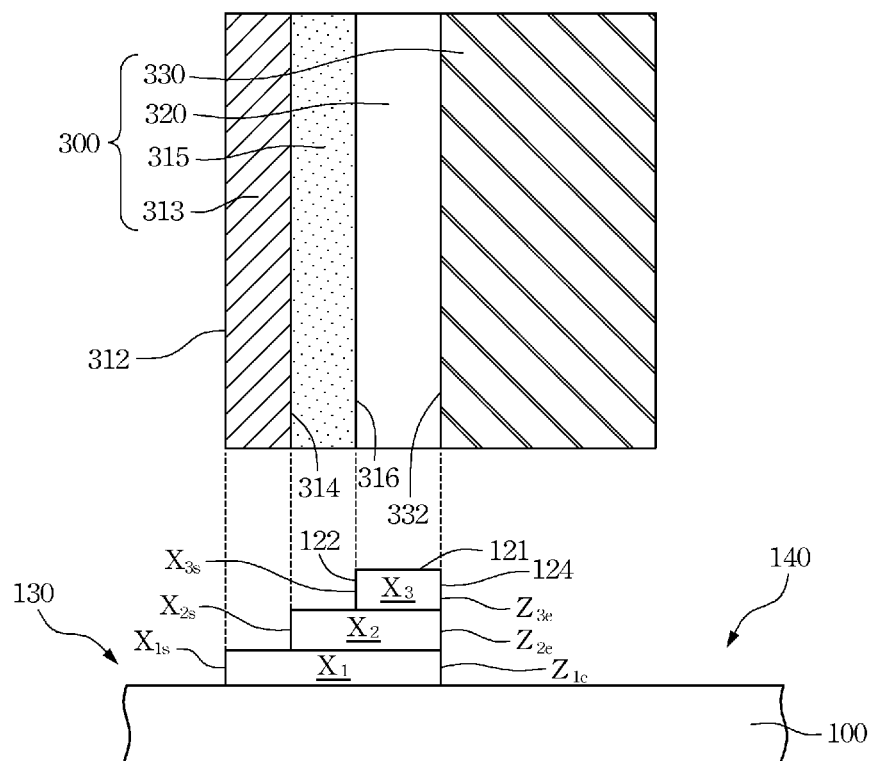


FIG. 10A

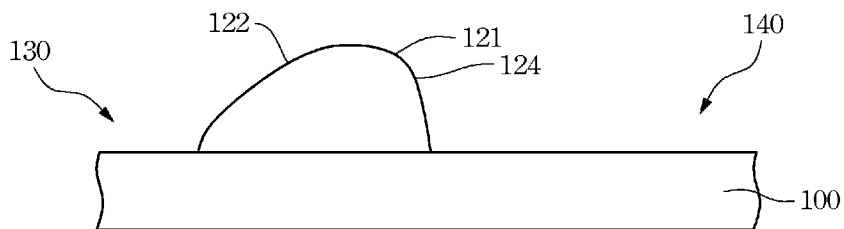


FIG. 10B

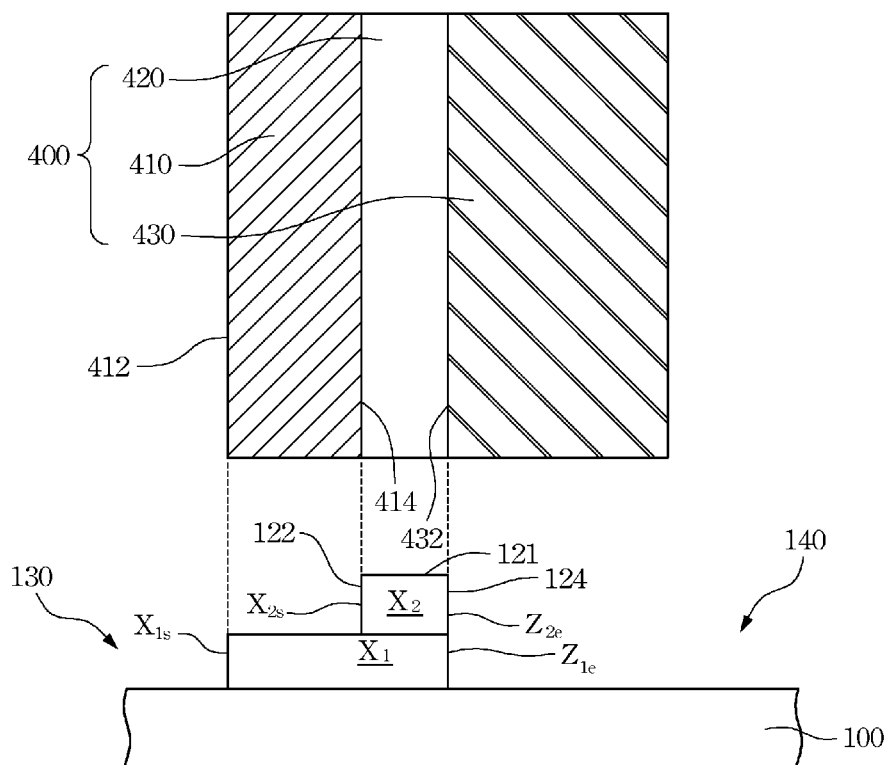


FIG. 11A

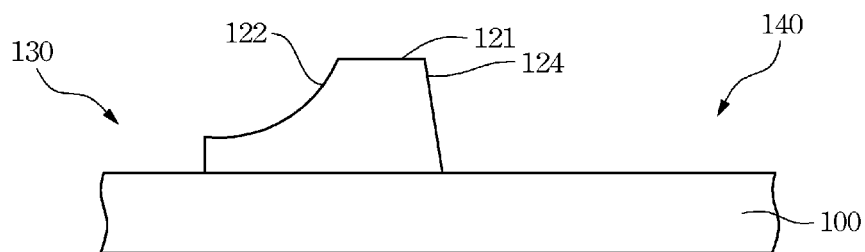


FIG. 11B

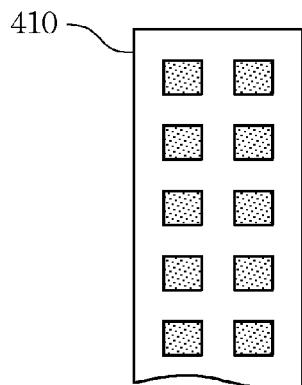


FIG. 12A

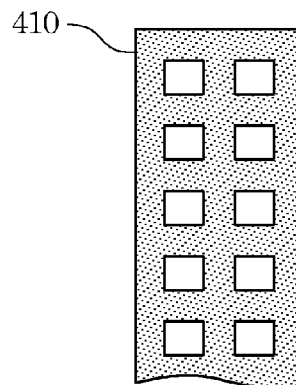


FIG. 12B

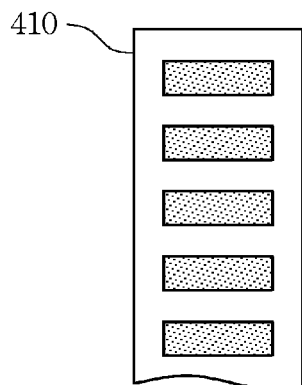


FIG. 12C

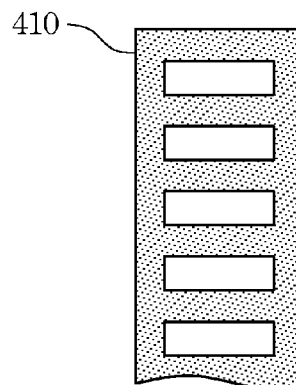


FIG. 12D

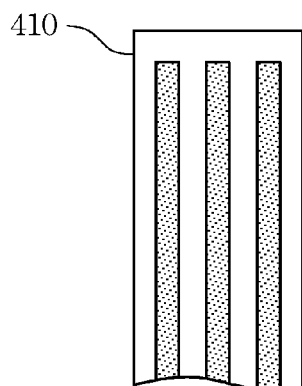


FIG. 12E

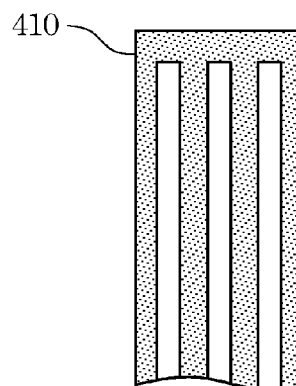


FIG. 12F

1

METHOD FOR MANUFACTURING THIN FILM TRANSISTOR ARRAY

RELATED APPLICATIONS

The present application is a division of U.S. application Ser. No. 12/648,127, filed Dec. 28, 2009, which claims priority to Taiwan application serial number 98122805, filed Jul. 6, 2009. All of these applications are incorporated herein by reference.

BACKGROUND

1. Field of Invention

The present invention relates to a display apparatus. More particularly, the present invention relates to a liquid crystal display (LCD).

2. Description of Related Art

With respect to a LCD, an aperture ratio of its pixel region directly affects the utilization rate of a backlight module, and also affects the display brightness of the LCD. One of the major factors affecting the aperture ratio is the area of a wall formed on a substrate of the LCD. Therefore, for increasing the aperture ratio, various techniques have been developed, such as COA (Color Filter ON Array), UHA (Ultra High Aperture) and IJP-COA (Ink-Jet Printing-Color Filter On Array), so as to reduce the areas of the walls.

With respect to the IJP-COA technique, a pixel region and a contact hole is divided by means of a wall of which the sidewalls have the same slopes. However, the wall having the same sidewall slopes causes a color resist overflowing out of the pixel region, thus causing a yield problem, further resulting in a broken wire problem when a transparent electrode covers the contact hole.

SUMMARY

Hence, an aspect of the present invention is to provide a method for manufacturing a thin film transistor (TFT) array in which a wall has at least two different sidewall slopes for meeting different requirements of a contact hole and a pixel region.

In accordance with one embodiment of the present invention, the method for manufacturing the TFT array includes the following steps of:

- (1) forming at least one thin film transistor on a substrate;
- (2) forming a wall material layer to cover the thin film transistor and the substrate; and
- (3) patterning the wall material layer by using at least one photomask to form a wall for separating a contact hole from a pixel region, wherein the wall has a first sidewall facing the contact hole and a second sidewall facing the pixel region and a slope of the first sidewall is gentler than a slope of the second sidewall;

wherein the patterning step includes:

- (3.1) moving the photomask relative to the substrate in a horizontal direction; and
- (3.2) using a plurality of patterns to perform multiple exposures on the wall material layer.

In accordance with another embodiment of the present invention, the method for manufacturing the TFT array includes the following steps of:

- (1) forming at least one thin film transistor on a substrate;
- (2) forming a wall material layer to cover the thin film transistor and the substrate; and
- (3) patterning the wall material layer by using a gray-tone mask (GTM) or a half-tone mask (HTM) to form a wall for

2

separating a contact hole from a pixel region, wherein a first sidewall of the wall facing the contact hole has a slope gentler than a slope of a second sidewall of the wall facing the pixel region.

It is to be understood that both the foregoing general description and the following detailed description are examples, and are intended to provide further explanation of the invention as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

These and other features, aspects, and advantages of the present invention will become better understood with regard to the following description, appended claims, and accompanying drawings where:

FIG. 1 to FIG. 6 are cross-sectional schematic views showing a flow process for manufacturing a TFT array according to one embodiment of the present invention;

FIG. 7 is an enlarged schematic view of the wall shown in FIG. 2;

FIG. 8A to FIG. 8B are schematic views showing a patterning step according to one embodiment of the present invention;

FIG. 9A to FIG. 9C are schematic views showing a patterning step according to another embodiment of the present invention;

FIG. 10A to FIG. 10B are schematic views showing a patterning step according to another embodiment of the present invention;

FIG. 11A to FIG. 11B are schematic views showing a patterning step according to another embodiment of the present invention; and

FIG. 12A to FIG. 12F are schematic top views showing a half-tone mask (HTM) according to the embodiment of the present invention.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

Reference will now be made in detail to the present preferred embodiments of the invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts.

FIG. 1 to FIG. 6 are cross-sectional views showing a flow process for manufacturing a TFT array according to one embodiment of the present invention. It should be understood that the steps disclosed in the present embodiment can be arranged in different sequences in accordance with actual needs besides the sequence those steps those whose sequences have been particularly specified, wherein all or part of the steps can be performed simultaneously.

Referring to FIG. 1, at least one TFT 110, and a lower electrode 117 and a dielectric layer 118 of a capacitor 115 are first formed on a substrate 100. Then, in accordance with situation requirements, a first protection layer 160 may be formed on the entire substrate 100, thereby protecting the TFT 110 from being affected by subsequent processes. It should be understood that the first protection layer is not a necessary element, and one of ordinary skill in the art may flexibly choose whether the first protection layer 116 should be formed in accordance with actual needs.

Thereafter, a wall 120 is formed on the substrate 110 to cover the TFT 110, the dielectric layer 118 of the capacitor 115, and the substrate 100, wherein the material forming the wall 120 can be varied in accordance with the requirements, and can be optionally an organic or inorganic material with

ink repellent (herein called hydrophobic or lipophilic) properties, and also can be a conductor or non-conductor.

Referring to FIG. 2, the wall 120 is patterned by using a photomask, thereby forming a first contact hole 130, a second contact hole 135 and a pixel region 140 on the wall 120. In other words, after the wall 120 is patterned, at least one first wall 121 and at least one second wall 125 are formed on the substrate 100, wherein the first wall 121 separates the first contact hole 130 from the pixel region 140, and the second wall 125 separates the pixel region 140 from the second contact hole 135.

Since the contact holes and the pixel regions require different sidewall slopes, in the present step, the exposure amounts at the contact holes and the pixel region can be controlled to make the sidewall slopes of the contact holes gentler than the sidewall slope of the pixel region. Using the first wall 121 shown in FIG. 2 as an example, the first wall 121 includes a first sidewall 122 facing towards the first contact hole 130; and a second sidewall 124 facing towards the pixel region 140, wherein the slope of the first sidewall 122 is gentler than the slope of the second sidewall 124. Similarly, with respect to the second sidewall 125, the second sidewall 125 also includes a first sidewall 126 facing towards the second contact hole 135; and a second sidewall 128 facing towards the pixel region 140, wherein the slope of the first sidewall 126 is gentler than the slope of the second sidewall 128.

Detailedly speaking, each of the slopes of the first wall 121 and the second wall 125 is defined as an angle included between a horizontal line of a base 123 and a straight line formed by connecting a corner of a sidewall at the base 123 and a top point of the sidewall. Using the first wall 121 shown in FIG. 7, the corners C and C' of the sidewalls at the base 123 are respectively connected to the top point D of the sidewalls 122 and 124 to form straight lines CD and C'D, and two angles θ_1 and θ_2 are included between the respective straight lines CD and C'D and the horizontal line of the base 123, as shown in FIG. 7, thereby determining the difference between the slope of the first sidewall 122 and the slope of the second sidewall 124. If the angle θ_1 is smaller than the angle θ_2 , then the slope of the first sidewall 122 is gentler than the slope of the second sidewall 124. Further, the slopes of the respective straight lines CD and C'D can be directly calculated to determine if the gradients of the sidewalls 122 and 124 are steep or gentle.

FIG. 8 to FIG. 12 are used as examples for explaining how to control the exposure amounts at the contact holes and the pixel region to make the sidewall slopes of the contact holes gentler than the sidewall slopes of the pixel region. It should be understood that, in the embodiments of the present invention, each of the walls can be formed from a negative photoresist, a positive photoresist or another photosensitive material, and also can be formed from an organic, inorganic, conductive or non-conductive material, and yet the embodiments of the present invention are not limited thereto. Hereinafter, a negative photoresist is used as an example for specifically explaining the implementation of the embodiments of the present invention.

Please refer to FIG. 8A and FIG. 8B. While the walls are patterned, a photomask 200 can be moved relative to the substrate 100 in a horizontal direction. The relative movement called herein can be: fixing the position of the photomask 200 and moving the substrate 100; or fixing the position of the substrate 100 and moving the photomask 200; or relatively moving both of the substrate 100 and the photomask 200. One of ordinary skill in the art should flexibly choose the method for implementing the present step in accordance with

actual needs. The photomask 200 includes patterns 210, 220 and 230. Each of the patterns 210, 220 and 230 includes a totally transparent zone A and totally light-blocking zones B and B', wherein the totally light-blocking zone B' is formed as a rectangle, and the totally transparent zone A is formed as a rectangular loop surrounding the totally light-blocking zone B', and the totally light-blocking zone B is formed as another rectangular loop surrounding the totally transparent zone A. The differences among the patterns 210, 220 and 230 reside in that: the area of the totally transparent zone A protruding from the totally light-blocking zone B' in the pattern 210 is greater in area than that in the pattern 220; and the area of the totally transparent zone A protruding from the totally light-blocking zone B' in the pattern 220 is greater than that in the pattern 230. For example, the distance in the pattern 210 between an end point O_{210} (at the intersection of the zone A_{210} and the zone B_{210}) and a horizontal point P_{210} (at the intersection of the zone A_{210} and the zone B'_{210}) is greater than the distance in the pattern 220 between an end point O_{220} (at the intersection of the zone A_{220} and the zone B_{220}) and a horizontal point P_{220} (at the intersection of the zone A_{220} and the zone B'_{220}); and the distance in the pattern 220 between an end point O_{220} (at the intersection of the zone A_{220} and the zone B_{220}) and a horizontal point P_{220} (at the intersection of the zone A_{220} and the zone B'_{220}) is greater than the distance in the pattern 230 between an end point O_{230} (at the intersection of the zone A_{230} and the zone B_{230}) and a horizontal point P_{230} (at the intersection of the zone A_{230} and the zone B'_{230}). Further, the area of the zone B'_{230} of the pattern 230 is greater than the area of the zone B'_{220} of the pattern 220, and the area of the zone B'_{220} of the pattern 220 is greater than the area of the zone B'_{210} of the pattern 210.

Please refer to FIG. 8A and FIG. 8B for explaining an exposure method of horizontally moving the photomask 200 on which the patterns 210, 220 and 230 with different exposure amounts at their respective zones A, B and B' are formed. A three-step stair structure shown in FIG. 8A formed by photoresist exposure is used as an example herein. The photomask 200 and the substrate 100 are disposed in parallel in a top and bottom arrangement, wherein the photomask 200 are disposed above the substrate 100. In the present embodiment, an exposure light source (not shown) is disposed above the photomask 200, and the first wall 121 is formed on the substrate 100. Then, an exposure step is performed on the first wall 121 by using the pattern 210 of the photomask 200. After the projection of the pattern 210 along a border AB'_{210} between the zone A_{210} and the zone B'_{210} is aligned with a predetermined start line X_{1s} of a first step X_1 of the first wall 121; and the projection of the pattern 210 along a border AB_{210} between the zone A_{210} and the zone B_{210} is aligned with a predetermined end line Z_{1e} of the first step X_1 of the first wall 121, a first exposure process is performed. Thereafter, the photomask 200 is moved horizontally at a speed until the projection of the pattern 220 along a border AB'_{220} between the zone A_{220} and the zone B'_{220} is aligned with a predetermined start line X_{2s} of a second step X_2 of the first wall 121; and the projection of the pattern 220 along a border AB_{220} between the zone A_{220} and the zone B_{220} is aligned with a predetermined end line Z_{2e} of the second step X_2 of the first wall 121, and then a second exposure step is performed. Thereafter, the photomask 200 is continued to be moved horizontally at a speed until the projection of the pattern 230 along a border AB'_{230} between the zone A_{230} and the zone B'_{230} is aligned with a predetermined start line X_{3s} of a third step X_3 of the first wall 121; and the projection of the pattern 230 along a border AB_{230} between the zone A_{230} and the zone B_{230} is aligned with a predetermined end line Z_{3e} of the

5

second step X_3 of the first wall 121, and then a third exposure step is performed. Thereafter, a development process is performed. Using a negative photoresist as an example, when the negative photoresist undergoes exposure, cross-linking phenomena will be caused to prevent the negative photoresist from being affecting by a developer in a subsequent process, thus retaining the negative photoresist. However, if the negative photoresist does not undergo exposure, no cross-linking phenomena will be caused, and thus the negative photoresist will disappear due to the function of the developer. Therefore, after the development process, the pattern as shown in FIG. 8A is obtained, wherein the first sidewall 122 of the first wall 121 receives the influences of different exposure amounts, and shows the stair structure since portions of the photoresist are washed away by the developer. However, since the second sidewall 124 of the first wall 121 and the pixel region 140 are aligned with the totally light-blocking zone B, the photoresist corresponding thereto is not affected by exposure and is entirely washed away by the developer, so that the photoresist in the pixel region 140 cannot be retained. Thereafter, a baking process is performed to reflow the photoresist, thereby forming the first sidewall 122 and the second sidewall 124 shown in FIG. 8B. It is noted that the projections of the predetermined end line Z_{2e} of the second step X_2 and that of the predetermined end line Z_{3e} of the second step X_3 both fall on the predetermined end line Z_{1e} of the first step X_1 , but the embodiments of the present invention are not limited thereto. In other embodiments, different designs can be used in accordance with different requirements. For example, the lines Z_{1e} , Z_{2e} and Z_{3e} are not overlapped together, or after development the pattern shows a stair structure with more than three steps or less than three steps.

Through the above processes, the slope of the first sidewall 122 in the contact hole 130 is gentler than that of the second sidewall 124 at the pixel region 140. The present embodiment also can use three photomasks individually for the respective patterns 210, 220 and 230, and also can adopt other patterns, such as polygons, circulars or irregular patterns, etc., but the embodiments of the present invention are not limited thereto.

The relative moving speed between the photomask 200 and the substrate 110 depends on actual requirements. In the present embodiment, the relative moving speed is ranged between 50 mm/sec and 300 mm/sec. It should be understood that the aforementioned process parameters are merely shown as examples for explanation, which are not used to limit the embodiments of the present invention. One of ordinary skill in the art should flexibly choose the appropriate ones in accordance with actual requirements.

Since the photomask 200 is moved relative to the substrate 100 in a horizontal direction during the exposure process, the patterns defining the wall are sequentially changed as shown by the pattern 210, the pattern 220 and the pattern 230. Consequently, after exposure, the wall can provide the sidewalls with two different slopes. For example, after exposure, the slope of the first sidewall 122 of the first wall 121 is gentler than that of the second sidewall 124 thereof. Detailedly speaking, using a negative photoresist as an example for explanation, when the negative photoresist undergoes exposure, cross-linking phenomena will be caused to prevent the negative photoresist from being affecting by a developer in a subsequent process, thus retaining the negative photoresist. However, if the negative photoresist does not undergo exposure, no cross-linking phenomena will be caused, and thus the negative photoresist will disappear due to the function of the developer. Thus, after exposure, the wall can provide the sidewalls with two different slopes. For example, after exposure, the first sidewall 122 of the first wall 121 receives the

6

influences of different exposure amounts A and B', and thus portions of the negative photoresist corresponding thereto do not undergo exposure and will be washed away by a developer. On the other hand, the second sidewall 124 of the first wall 121 receives the influence of one single exposure amount B, and all of the negative photoresist corresponding thereto does not undergo exposure and thus will be washed away by the developer since no cross-line phenomena is caused. Consequently, a phenomena can be obtained that the slope of the first sidewall 122 of the first wall 121 is gentler than that of the second sidewall 124 thereof.

Further, at least one gray-tone mask (GTM) also can be disposed on the photomask in accordance with the situation, thereby further adjusting the exposure amounts on both sidewalls of the wall. For example, at the totally transparent zone A of the photomask shown in FIG. 8A, a GTM or half-tone mask (HTM) can be optionally adopted. For example, as shown in FIG. 9A to FIG. 9C, with respect to the first wall 121, at least one GTM pattern zone 310 can be disposed on the photomask. Thus, after exposure and development, since the first wall 121 receives the influences of different exposure amounts, the slope of the first sidewall 122 of the first wall 121 is gentler than that of the second sidewall 124 thereof.

It should be understood that FIG. 9A is a 3-D schematic diagram exemplarily showing the photomask and the substrate during actual exposure. In other embodiments, the photomask and the substrate are shown in top and side views (such as FIG. 8A, FIG. 9B, FIG. 10A and FIG. 11A), so as to clearly depict the relative positions of the photomask and the substrate.

Using a two-step stair structure formed by the photoresist after exposure as an example, a photomask 300 shown in FIG. 9B may include a GTM pattern zone 310, a totally transparent zone 320 and a totally light-blocking zone 330 arranged in sequence. A light transmittance of the GTM pattern zone 310 can be ranged between 10% and 80% or preferably between 30% and 50%, for example. The light transmittance of the totally transparent zone 320 can be, for example, 100%, and the light transmittance of the totally light-blocking zone 330 can be, for example, 0%. Prior to exposure, the projection of a border 312 of the GTM pattern zone 310 towards the substrate 100 is first aligned with a predetermined start line X_{1s} of a first step X_1 of the first wall 121; the projection of a border 316 at the intersection of the GTM pattern zone 310 and the totally transparent zone 320 is aligned with a predetermined start line X_{2s} of a second step X_2 of the first wall 121; and the projection of a border 332 at the intersection of the totally transparent zone 320 and the totally light-blocking zone 330 is aligned with predetermined end lines Z_{1e} and Z_{2e} of the first step X_1 and the second step X_2 of the first wall 121. Thereafter, an exposure process is performed.

Since the GTM pattern zone 310 is aligned with the first sidewall 122 (or referred to as the sidewall of the contact hole) of the first wall 121 during the exposure process, only a portion but not all of the photoresist will be washed away after development. However, since all of the pixel region 140 and the second sidewall 124 of the first wall 121 are aligned with the totally light-blocking zone 330 during the entire exposure process, the photoresist corresponding thereto does not undergo exposure and are washed away by a developer entirely, so that the photoresist at the pixel region 140 cannot be retained. Thereafter, a baking process is performed to reflow the photoresist, thereby forming the first sidewall 122 and the second sidewall 124 shown in FIG. 9C.

Besides the two-step stair structure, after exposure, the photoresist also may form a three-step stair structure. For example, as shown in FIG. 10A and FIG. 10B, the photomask

300 shown in FIG. 10A may include a first GTM pattern zone 313, a second GTM pattern zone 315, a totally transparent zone 320 and a totally light-blocking zone 330 arranged in sequence. A light transmittance of the first GTM pattern zone 313 can be ranged between 10% and 40% or preferably between 25% and 35%, for example. A light transmittance of the second GTM pattern zone 315 can be ranged between 40% and 80% or preferably between 50% and 70%, for example. The light transmittance of the totally transparent zone 320 can be, for example, 100%, and the light transmittance of the totally light-blocking zone 330 can be, for example, 0%. Prior to exposure, the projection of a border 312 of the first GTM pattern zone 313 towards the substrate 100 is first aligned with a predetermined start line X_{1s} of a first step X_1 of the first wall 121; the projection of a border 314 at the intersection of the first GTM pattern zone 313 and the second GTM pattern zone 315 is aligned with a predetermined start line X_{2s} of a second step X_2 of the first wall 121; the projection of a border 316 at the intersection of the second GTM pattern zone 315 and the totally transparent zone 320 is aligned with a predetermined start line X_{3s} of a second step X_3 of the first wall 121; and the projection of a border 332 at the intersection of the totally transparent zone 320 and the totally light-blocking zone 330 is aligned with predetermined end lines Z_{1e} , Z_{2e} and Z_{3e} of the first step X_1 , the second step X_2 and the third step X_3 of the first wall 121. Thereafter, an exposure process is performed.

Since the first GTM pattern zone 313 and the second GTM pattern zone 315 are aligned sequentially with the first sidewall 122 (or referred to as the sidewall of the contact hole) of the first wall 121 during the exposure process, the first sidewall 122 of the first wall 121 receives the influences of different exposure amounts, so that portions of the photoresist are washed away by a developer after development, thus showing a step shape. However, since all of the pixel region 140 and the second sidewall 124 of the first wall 121 are aligned with the totally light-blocking zone 330 during the entire exposure process, the photoresist corresponding thereto does not undergo exposure and are washed away by a developer entirely, so that the photoresist at the pixel region 140 cannot be retained. Thereafter, a baking process is performed to reflow the photoresist, thereby forming the first sidewall 122 and the second sidewall 124 shown in FIG. 10C.

Further, there are other designs used for controlling exposure intensities, so as to achieve the efficacy of forming a wall with two different sidewall slopes. In other embodiments, a HTM can be used to perform exposure on the sidewall, which also can make the slope of the first sidewall 122 of the wall 121 gentler than that of the second sidewall 124, i.e. the sidewall slope of the contact hole is gentler than the sidewall slope at the pixel region.

Using a two-step stair structure formed by the photoresist after exposure as an example, a photomask 400 shown in FIG. 11A may include a HTM pattern zone 410, a totally transparent zone 420 and a totally light-blocking zone 430 arranged in sequence. The light transmittance of the HTM pattern zone 410 can be determined in accordance with actual needs, and the light transmittance of the totally transparent zone 420 can be, for example, 100%, and the light transmittance of the totally light-blocking zone 430 can be, for example, 0%. Prior to exposure, the projection of a border 412 of the HTM pattern zone 410 towards the substrate 100 is first aligned with a predetermined start line X_{1s} of a first step X_1 of the first wall 121; the projection of a border 414 at the intersection of the HTM pattern zone 410 and the totally transparent zone 420 is aligned with a predetermined start line X_{2s} of a second step X_2 of the first wall 121; and the projection of a border 432 at the

intersection of the totally transparent zone 420 and the totally light-blocking zone 430 is aligned with predetermined end lines Z_{1e} and Z_{2e} of the first step X_1 and the second step X_2 of the first wall 121. Thereafter, an exposure process is performed.

Similarly, since the HTM pattern zone 410 is aligned with the first sidewall 122 (or referred to as the sidewall of the contact hole) of the first wall 121 during the exposure process, only a portion but not all of the photoresist will be washed away after development. However, since all of the pixel region 140 and the second sidewall 124 of the first wall 121 are aligned with the totally light-blocking zone 430 during the entire exposure process, the photoresist corresponding thereto does not undergo exposure and are washed away by a developer entirely, so that the photoresist at the pixel region 140 cannot be retained. Thereafter, a baking process is performed to reflow the photoresist, thereby forming the first sidewall 122 and the second sidewall 124 shown in FIG. 11B.

The aforementioned HTM pattern zone 410 can be designed in accordance with actual needs. For example, the HTM pattern zone 410 can be designed as a dot/mash type arrangement, as shown in FIG. 12A and FIG. 12B, wherein dotted areas stand for light-blocking areas (their light-transmittances are 0%), and vacant areas stand for transparent areas (their light-transmittances are 100%). Certainly, the HTM pattern zone 410 can be designed as a slit/line type arrangement, as shown in FIG. 12C, FIG. 12D, FIG. 12E and FIG. 12F, wherein dotted areas stand for light-blocking areas (their light-transmittances are 0%), and vacant areas stand for transparent areas (their light-transmittances are 100%).

The material forming the aforementioned wall can be a photosensitive resin containing a black pigment, wherein the black pigment can be such as carbon black, titanium black, lead black, metal oxide, iron oxide or titanium oxide. As to other process parameters related to patterning the wall, they should be varied in accordance with the composition of the photosensitive resin. In the present embodiment, an exposure amount for patterning the wall can be ranged between 30 mJ/cm² and 1000 mJ/cm²; or 30 mJ/cm² and 100 mJ/cm², and an illumination intensity therefor can be ranged between 20 mW/cm² and 60 mW/cm², and an exposure time therefor can be ranged between 0.5 sec and 50 sec. It should be understood that the aforementioned process parameters are merely stated as an example, and the material forming the wall also can be a conductive material such as copper, molybdenum; or a non-conductive material such as a resin material, but the embodiments of the present invention are not limited thereto. One of ordinary skill in the art should flexibly choose the material for forming the wall in accordance with actual needs.

Please return to FIG. 3. After the wall 120 is patterned, a step is performed for ink-jet printing (IJP) at least one color resist 150 into the pixel region 140. In other words, after the step is performed, the color resist 150 is filled in the pixel region 140 to provide the required filtering function.

Referring to FIG. 4, then, a second protection layer 165 can be formed on the substrate 100. The second protection layer 165 may cover the entire structure currently formed on the substrate 100 (for example, the color resist 150 and the wall 120), thereby preventing the structure from being affected by the subsequent processes.

The material forming the aforementioned first and second protection layers 160 and 165 can be (include but not limited): organic layers, silicon nitride, silicon oxide or another suitable protection material. Further, the aforementioned first and second protection layers 160 and 165 are necessary elements, and one of ordinary skill in the art should flexibly choose if it

is necessary to form the first and second protection layers **160** and **165** in accordance with actual needs.

Referring to FIG. 5, then, a lithographic etching can be used to remove the first and second protection layers **160** and **165** in the first contact hole **130**, thereby enabling a transparent electrode **180** subsequently formed to electrically connect to a drain electrode **112** of the TFT **110**. Detailedly speaking, a photoresist **170** is first formed on the substrate **110**, and then an etching process is used to remove the first and second protection layers **160** and **165** in the first contact hole **130**. After the first and second protection layers **160** and **165** are removed from the first contact hole **130**, the photoresist **170** can be optionally removed, thereby benefiting the subsequent processes.

Referring to FIG. 6, then, the transparent electrode **180** can be formed on the substrate **100** to cover the wall **120**, the first contact hole **130**, the second contact hole **135** and the color resist **150**. Detailedly speaking, the aforementioned transparent electrode **180** can be electrically connected to the drain electrode **112** of the TFT **110** via the first contact hole **130**. Further, the transparent electrode **180** also may be extended to the dielectric layer **118** of the capacitor **115** via the second hole **135** and used as an upper electrode **119** of the capacitor **115**.

Another technical aspect of the present invention is the TFT array made by using the aforementioned manufacturing method. As shown in FIG. 6, a TFT array includes the substrate **100**, the TFT **110**, the first wall **121**, the transparent electrode **180** and the color resist **150**. The TFT is disposed on the substrate **100**. The first wall **121** is disposed on the substrate **100**, and at least separates the first contact hole **130** from the pixel region **140** on the substrate **100**, wherein the drain electrode **112** of the TFT **110** is exposed through the first contact hole **130**. The first wall **121** includes the first wall **112** facing towards the first contact hole **130** and the second wall **124** facing towards the pixel region **140**, wherein the slope of the first wall **121** is gentler than that of the second wall **124**. The transparent electrode **180** is electrically connected to the drain electrode **112** of the TFT **110** via the first contact hole **130**. The color resist **150** is filled in the pixel region **140**.

Further, the TFT array shown in FIG. 6 further includes the capacitor **115** and the second wall **125**. The capacitor **115** is disposed on the substrate **100**, and includes the lower electrode **117**, the dielectric layer **118** and the upper electrode **119**, wherein the dielectric layer **118** is disposed between the lower electrode **117** and the upper electrode **119**. The second wall **125** is disposed on the substrate **100**, and separates the pixel region **140** from the second contact hole **135**, wherein the dielectric layer **118** of the capacitor **115** is exposed through the contact hole **135**, and the transparent electrode **180** is extended to the dielectric layer **118** of the capacitor **115** via the second contact hole **135** and used as an upper electrode **119** of the capacitor **115**. The second wall **125** includes the first sidewall **126** facing towards the second contact hole **135** and the second wall **128** facing towards the pixel region **140**, wherein the slope of the first sidewall **126** is gentler than that of the second sidewall **128**.

With respect to the first wall **121**, a difference between the slope of the first sidewall **122** and that of the second sidewall **124** can be ranged between 10° and 60° or between 10° and 30°. Similarly, with respect to the second wall **125**, a difference between the slope of the first sidewall **126** and that of the second sidewall **128** also can be ranged between 10° and 60° or between 10° and 30°.

Further, with respect to the first wall **121**, the slope of the first sidewall **122** is preferably ranged between 10° and 70° or between 20° and 60°, and the slope of the second sidewall **124**

is preferably ranged between 70° and 100° or between 70° and 90°. Similarly, with respect to the second wall **125**, the slope of the first sidewall **126** is preferably between 10° and 70° or between 20° and 60°, and the slope of the second sidewall **128** is preferably ranged between 70° and 100° or between 70° and 90°.

Further, in the embodiments of the present invention, when the wall is being patterned, the photomask and the substrate can be moved independently in a horizontal direction, or both can be moved at simultaneously in the same or opposite horizontal directions, thereby making the sidewall slope of the contact hole gentler than the sidewall slope at the pixel region. However, the embodiments of the present invention are not limited thereto.

It should be understood that the aforementioned slope values are merely stated as examples, and are not used to limit the embodiments of the present invention. One of ordinary skill in the art should flexibly choose the slope values of the first and second sidewalls in accordance with actual needs.

It will be apparent to those skilled in the art that various modifications and variations can be made to the structure of the present invention without departing from the scope or spirit of the invention. In view of the foregoing, it is intended that the present invention cover modifications and variations of this invention provided they fall within the scope of the following claims and their equivalents.

What is claimed is:

1. A method for manufacturing a thin film transistor array, the method comprising:

forming at least one thin film transistor on a substrate;
forming a wall material layer to cover the thin film transistor and the substrate; and
patterning the wall material layer by using at least one photomask to form a wall for separating a contact hole from a pixel region, wherein the wall has a first sidewall facing the contact hole and a second sidewall facing the pixel region and a slope of the first sidewall is gentler than a slope of the second sidewall;
wherein the patterning step includes:
moving the photomask relative to the substrate in a horizontal direction; and
using a plurality of patterns to perform multiple exposures on the wall material layer.

2. The method as claimed in claim 1, wherein the step of moving the photomask relative to the substrate in the horizontal direction is selected from one of the steps of:

fixing the position of the photomask and moving the substrate;
fixing the position of the substrate and moving the photomask; and
moving the substrate and the photomask.

3. The method as claimed in claim 1, wherein the plurality of patterns is disposed on the photomask.

4. The method as claimed in claim 1, wherein each of the patterns comprises:

a first totally light-blocking zone formed as a rectangle;
a totally transparent zone formed as a first rectangular loop surrounding the first totally light-blocking zone; and
a second totally light-blocking zone formed as a second rectangular loop surrounding the totally transparent zone.

5. The method as claimed in claim 4, wherein the first totally light-blocking zones of the patterns are different in area.

6. The method as claimed in claim 1, wherein the plurality of patterns is disposed on a plurality of the photomasks, respectively.

11

7. The method as claimed in claim 1, wherein a relative moving speed between the photomask and the substrate is ranged between 50 mm/sec and 300 mm/sec.

8. The method as claimed in claim 1, wherein an exposure amount for patterning the wall material layer is ranged between 30 mJ/cm² and 1000 mJ/cm².

9. The method as claimed in claim 1, wherein an illumination intensity for patterning the wall material layer is ranged between 20 mW/cm² and 60 mW/cm².

10. The method as claimed in claim 1, wherein an exposure time for patterning the wall material layer is ranged between 0.5 sec and 50 sec.

11. The method as claimed in claim 1, wherein the wall is formed from a negative photoresist.

12. The method as claimed in claim 1, further comprising: ink-jet printing (IJP) at least one color resist into the pixel region.

13. The method as claimed in claim 12, further comprising: forming a transparent electrode to cover the wall, the contact hole and the color resist.

14. A method for manufacturing a thin film transistor array, the method comprising:

forming at least one thin film transistor on a substrate;
forming a wall material layer to cover the thin film transistor and the substrate; and

patterning the wall material layer by using a gray-tone mask (GTM) or a half-tone mask (HTM) to form a wall for separating a contact hole from a pixel region, wherein a first sidewall of the wall facing the contact hole has a slope gentler than a slope of a second sidewall of the wall facing the pixel region.

15. The method as claimed in claim 14, wherein the gray-tone mask comprises a GTM pattern zone corresponding to the first sidewall and a totally light-blocking zone corresponding to the second sidewall.

12

16. The method as claimed in claim 15, wherein a light transmittance of the GTM pattern zone is ranged between 10% and 80%.

17. The method as claimed in claim 14, wherein the gray-tone mask comprises a first GTM pattern zone and a second GTM pattern zone sequentially corresponding to the first sidewall of the contact hole.

18. The method as claimed in claim 17, wherein a light transmittance of the first GTM pattern zone is ranged between 10% and 40%.

19. The method as claimed in claim 17, wherein a light transmittance of the second GTM pattern zone is ranged between 40% and 80%.

20. The method as claimed in claim 14, wherein the half-tone mask comprises a HTM pattern zone corresponding to the first sidewall and a totally light-blocking zone corresponding to the second sidewall.

21. The method as claimed in claim 14, wherein an exposure amount for patterning the wall material layer is ranged between 30 mJ/cm² and 1000 mJ/cm².

22. The method as claimed in claim 14, wherein an illumination intensity for patterning the wall material layer is ranged between 20 mW/cm² and 60 mW/cm².

23. The method as claimed in claim 14, wherein an exposure time for patterning the wall material layer is ranged between 0.5 sec and 50 sec.

24. The method as claimed in claim 14, wherein the wall is formed from a negative photoresist.

25. The method as claimed in claim 14, further comprising: ink-jet printing at least one color resist into the pixel region.

26. The method as claimed in claim 25, further comprising: forming a transparent electrode to cover the wall, the contact hole and the color resist.

* * * * *